Quantitative scanning thermal microscopy studies of the influence of interfaces and heat transport anisotropy in 2D materials



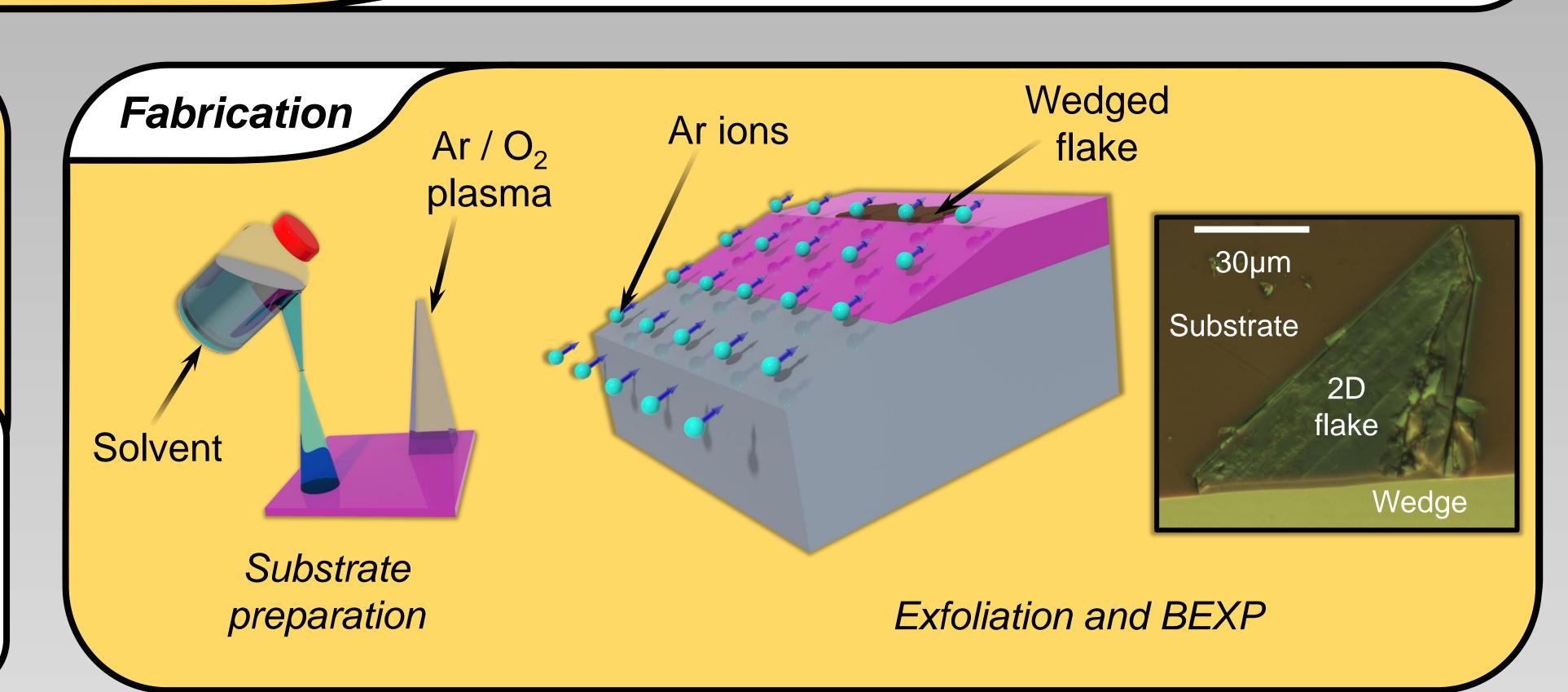
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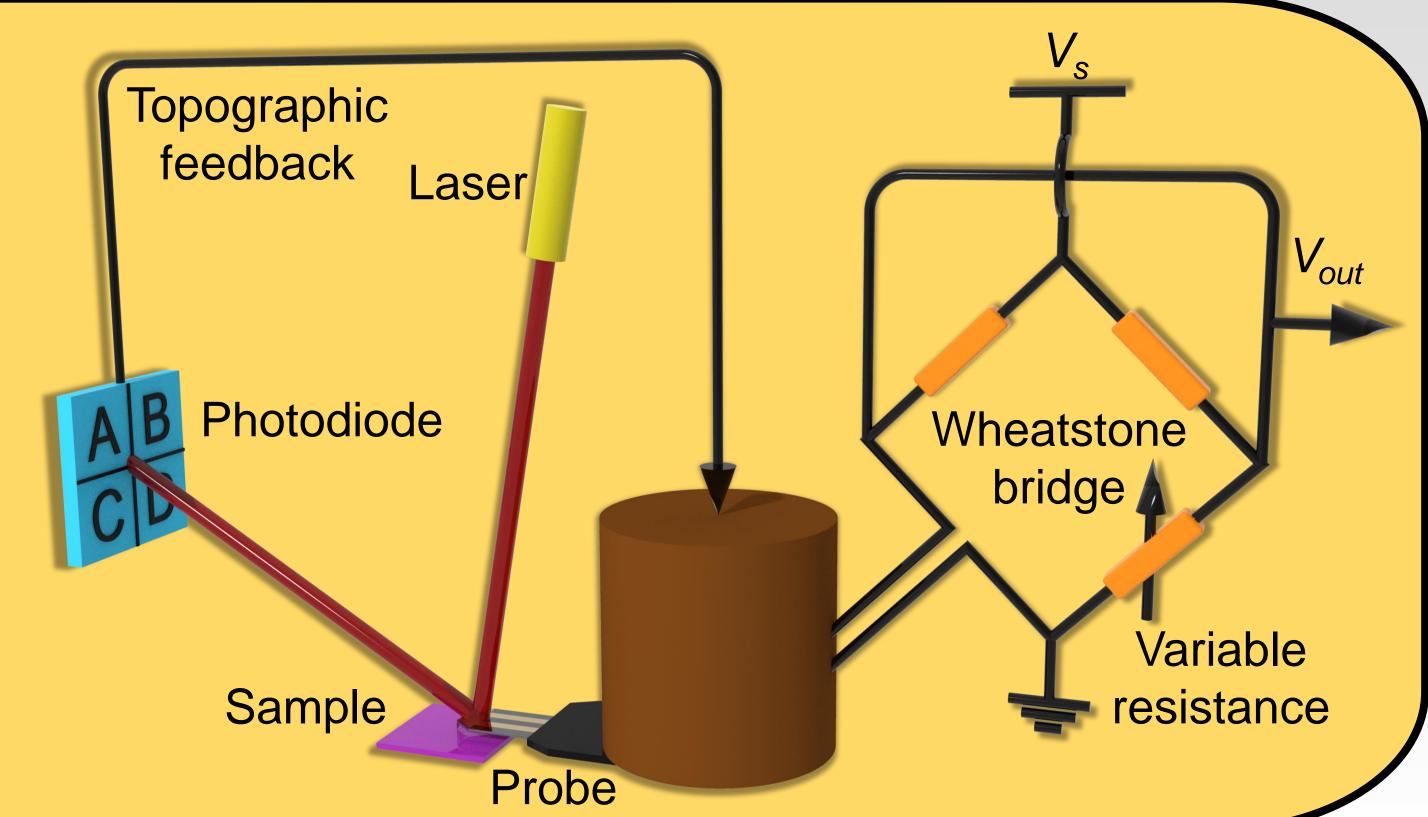
## Introduction

- ? Intrinsic anisotropy in bi-dimensional materials.1
- ? Interface / substrate role in the heat transport.<sup>2</sup>
- ? True *nanoscale resolution* of thermal properties depending on thickness.<sup>3</sup>
- Thermal transport in anisotropic graphene, γ-InSe, and perovskite.
- ☐ Interface effects on Si and SiO₂ substrates.
- ☐ Quantification of anisotropic thermal conductivities and interfacial thermal resistivity.

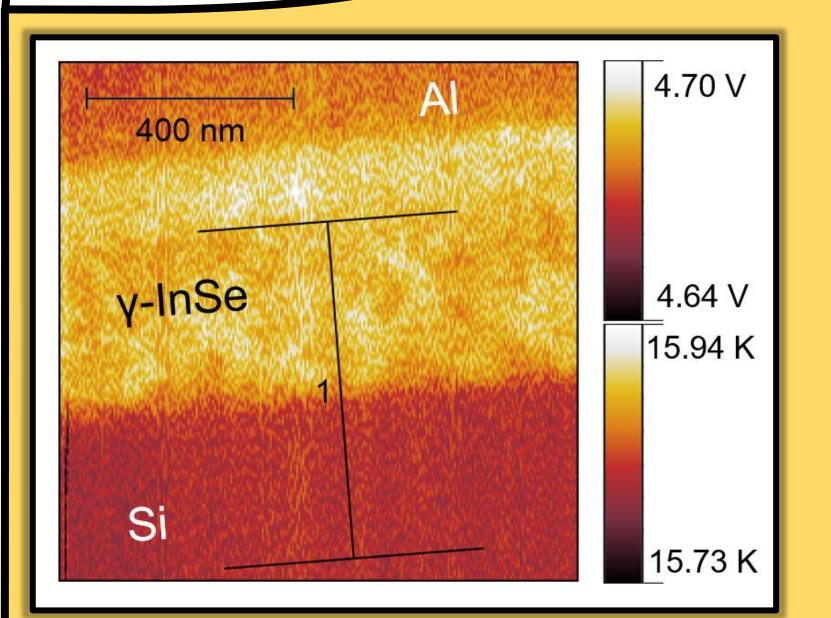


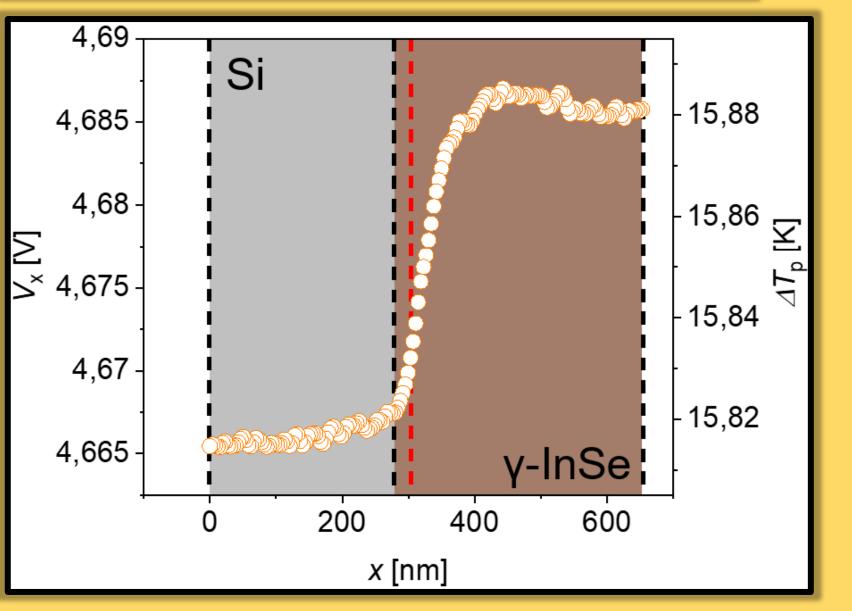
## Characterization

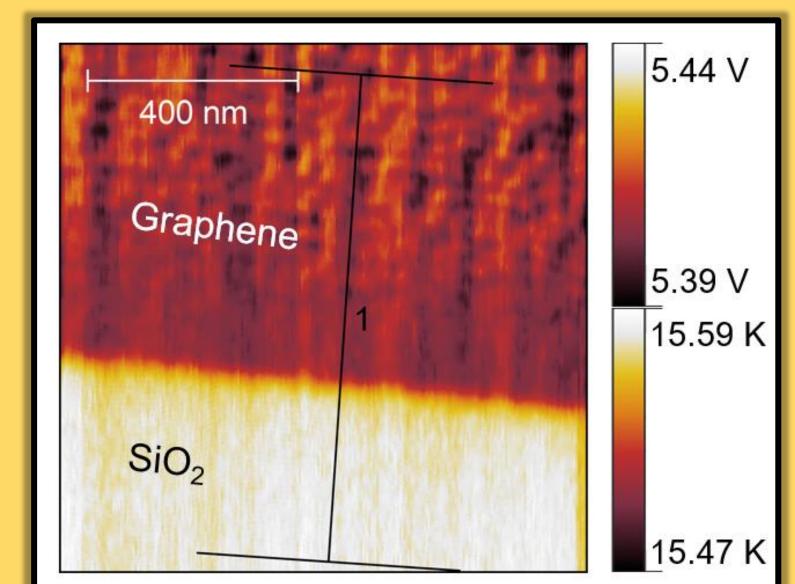
- ☐ HV-SThM (see right scheme) performed under high vacuum conditions and room temperature.
- □ SThM's probe incorporates a resistive heater receiving constant power via a DC-AC Wheatstone bridge.
- $\Box$   $V_{out} \propto T_{probe} \rightarrow T_{probe}$  changes due to variations of the probe-sample heat flow.
- ☐ By moving the probe across the sample surface, a quantitative map of the sample heat transport is obtained.<sup>4</sup>

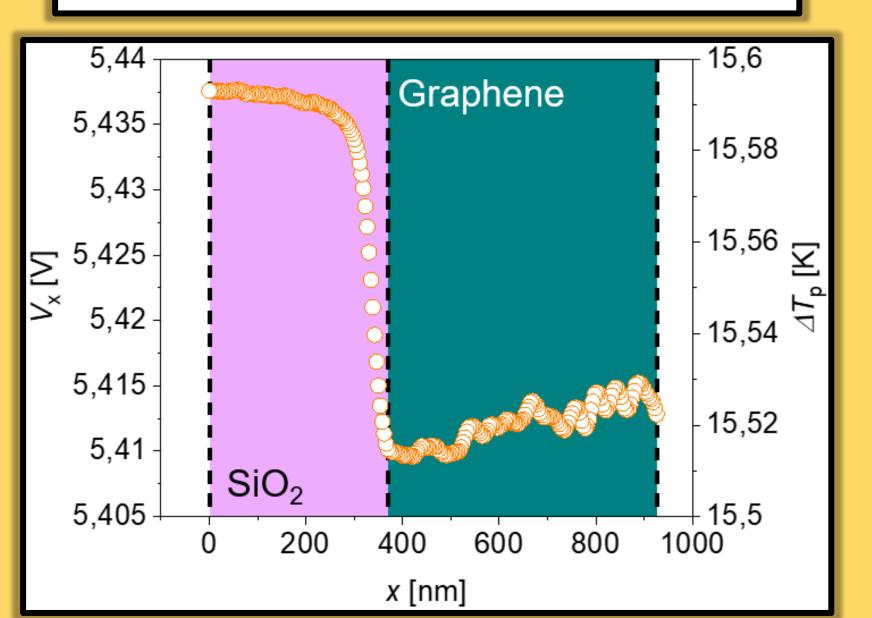


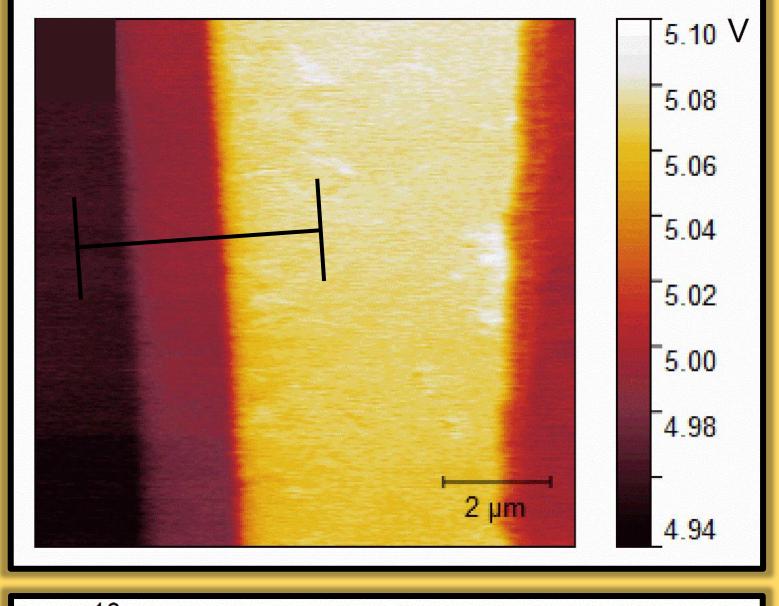
## Results

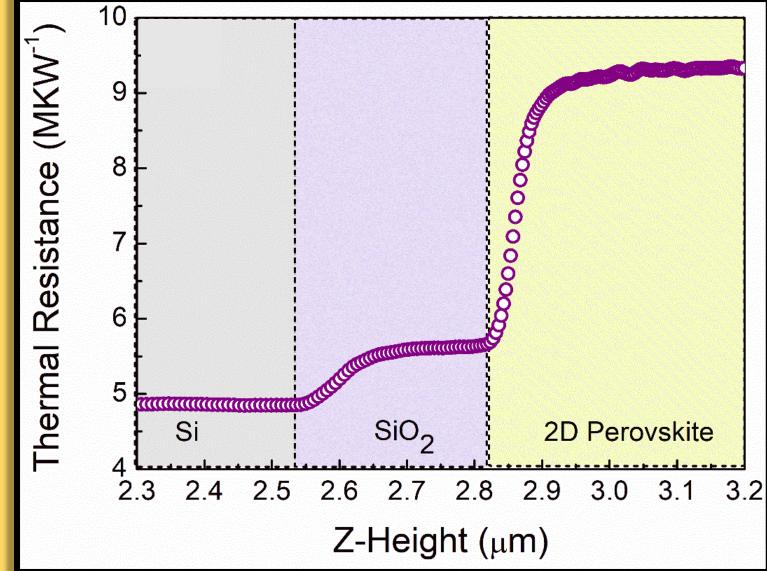












- $k_z$  $k_{xy}$ r<sub>int</sub> Materials [Wm<sup>-1</sup>K<sup>-1</sup>] [Wm<sup>-1</sup>K<sup>-1</sup>] [Km<sup>2</sup>W<sup>-1</sup>] [nm] 9.60×10<sup>-11</sup> y-InSe/Si 2.16 0.89 8.29 Perovskite /SiO<sub>2</sub> 55 100×10<sup>-11</sup> 0.13 5.15 0.45
- $\checkmark$   $r_{int}$  affects heat transport up to a limit, then it becomes negligible.
- ✓ Record-low anisotropic k for novel TE devices.
- ✓ True nanoscale resolution of heat transport features.

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## References

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- 4. Evangeli, C. et al. *Adv. Electron. Mater.* **5** (2019).





